

Onur Beker

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EDUCATION

Bogazici University

Electrical and Electronics Engineering, Junior
GPA: 3.93/4.00

2014 - Present

Tsukuba University

Exchange Student

2017 - 2018

Izmir Science High School

High School

2010 - 2014

RESEARCH EXPERIENCE

Max Planck Institute for Intelligent Systems

Research Intern at Physical Intelligence Department

June 2018 – September 2018

Stuttgart, Germany

- Designed a new method for the self-assembly and actuation of microrobots, using dielectrophoresis. Details of our work can be found in the corresponding article in Nature Materials.

Harvard-MIT Health Sciences & Technology/MGH, Athinoula A. Martinos Center for Biomedical Imaging

Research Intern at MR Physics and Instrumentation Group

June 2019 – September 2019

Boston, U.S

- Built an MRI artifact reduction method that uses only scan-specific data. My work there is summarized in the corresponding ISMRM abstracts.

PUBLICATIONS

- Yunus Alapan, Berk Yigit, **Onur Beker**, Ahmet F. Demirörs, Metin Sitti. “Shape-encoded programmable dynamic assembly of mobile micromachines”. *Nature Materials*, 2019. [link]
- **Onur Beker**, Congyu Liao, Jaejin Cho, Zijing Zhang, Kawin Setsompop, and Berkin Bilgic. “Scan-specific, Parameter-free Artifact Reduction in K-space (SPARK)”. (*submitted to*) *ISMRM*, 2020. [link]
- Jaejin Cho, Congyu Liao, Zijing Zhang, Wei-Ching Lo, Jinmin Xu, **Onur Beker**, Kawin Setsompop, and Berkin Bilgic. “Highly Accelerated EPI with Wave Encoding and Multi-shot Simultaneous MultiSlice Imaging”. (*submitted to*) *ISMRM*, 2020. [link]

SCHOLARSHIPS AND AWARDS

JASSO Scholarship for Short Term Study in Japan (2017 – 2018)

Awarded by the Japanese Ministry of Education, Culture, Sports, Science and Technology.

BUMED Extensive Success Scholarship (2014 – 2019)

Awarded by Bogazici University Alumni Association

Merit Based Prime Ministry Scholarship for Higher Education (2014 – 2019)

Awarded by Turkish Government for 65th degree in Undergraduate Placement Examination (LYS)

SKILLS

- **Programming:** Python, MATLAB, C/C++, Java, VHDL
- **Python:** NumPy, SciPy, Pytorch, Tensorflow, Keras
- **Tools:** Solidworks, COMSOL, PSpice, XILINX
- **Lab Work:** Microscopy, Nanoscribe, Image-J
- **Other:** Linux, Shell Scripts, Microsoft Office and other common applications for Windows

LANGUAGES

- **English:** Professional, (TOEFL IBT score: 112/120, GRE Verbal Score: 163/170)
- **Turkish:** Native Speaker
- **Japanese:** Conversational